

**A HIGH PERFORMANCE INTERPOSER FOR A CHIP PACKAGE
USING DEFORMABLE BUTTON CONTACTS**

ABSTRACT OF THE DISCLOSURE

5 An interposer includes an array of buttons on a carrier having a proximity to each other that allows contact between two adjacent buttons to occur when at least one of the two adjacent buttons is axially compressed above a predetermined threshold. The chip package includes a chip having a first surface and a second surface, a printed circuit board having a first surface and a second surface, and an interposer having an array of buttons between the chip and the printed circuit board. The first surfaces are closer to each other than the second surfaces.

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